

8.3.99



To the Honorable Commissioner of Patents and Trademarks

copies or copy thereof.

101118287

1 Name of conveying party(ies):  
Kuo-Hsiu Teng and Tseng-Hsuan  
Huang

2 Name and address of receiving party(ies):  
Taiwan Semiconductor Manufacturing  
Company Ltd.  
No. 121 Park Avenue 3  
Science-Based Industrial Park  
Hsin-Chu, Taiwan, R.O.C.

3 Nature of conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other:  
Execution Date: 05-20-99

Additional name(s) & address(es) attached  Yes  No

10504 U.S. PTO  
09/366233  
08/03/99

4 Application number(s) or patent number(s): **09366233**  
If this document is being filed together with a new application, the execution date of the application is: 05-20-99

A. Patent Application No(s).

B. Patent No(s)

Additional numbers attached?  Yes  No

5 Name and address of party to whom correspondence concerning document should be mailed:  
RANDY W. TUNG  
Tung & Associates  
838 W. Long Lake Road  
Suite 120  
Bloomfield Hills, Michigan 48302

6 Total number of applications and patents involved:  
1

7 Total fee (37 CFR 3.41) \$40.00

Enclosed  
 Authorized to be charged to deposit account

8 Deposit Account Number: 50-0484

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9 Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

RandyW. Tung  
Name of Person Signing  
Registration No. 31,311

Signature

8/3/99  
Date

Total number of pages including cover sheet, attachments, and document: \_\_\_\_\_

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents & Trademarks, Box Assignments  
Washington, D.C. 20231

08/11/1999 SCANNED 00000053 09366233

03 FC:501

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ASSIGNMENT

WHEREAS, we, KUO-HSIU TENG AND TSENG-HSUAN HUANG have invented certain improvements in SLOTTED RETAINING RING FOR POLISHING HEAD AND METHOD OF USING for which we are about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, we, KUO-HSIU TENG AND TSENG-HSUAN HUANG, by these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the United States of America and all foreign countries, the entire right, title and interest, including all priority rights under the International Convention associated with each country of the Union, in and to said invention as described in the patent application executed by us on the 20<sup>th</sup> day of May, 19    , preparatory to obtaining Letters Patent of the United States thereon, and in and to said application and any Letters Patent that may be granted in pursuance of said application and any divisional, continuation or continuation-in-part application thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

KUO-HSIU Teng  
KUO-HSIU TENG

Tseng-hsuan Huang  
TSENG-HSUAN HUANG

**TUNG & ASSOCIATES**  
**838 W. Long Lake Road**  
**Suite 120**  
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